

1.Description

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

2.2Features

- High power version of industry Standard SOT-23 package
- High performance trench technology for extremely low $R_{DS(ON)}$

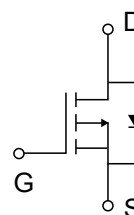
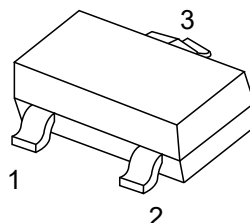
2.1Features

- $V_{DS(V)} = -30V$
- $I_D = -2 A (V_{GS} = -10V)$
- $R_{DS(ON)} < 80m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} < 125m\Omega (V_{GS} = -4.5V)$
- Low gate charge (6.2 nC typical)
- higher power handling capability

3.Pinning information

Pin	Symbol	Description
1	G	GATE
2	S	SOURCE
3	D	DRAIN

SOT-23



4.Maximum ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current – Continuous (Note 1a) – Pulsed	I_D	-2	A
		-10	
Power Dissipation for Single Operation (Note 1a) (Note 1b)	P_D	0.5	W
		0.46	
Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$
Thermal Characteristics			
Thermal Resistance, Junction-to-Ambient (Note 1a)	$R_{\theta JA}$	250	$^\circ C/W$
Thermal Resistance, Junction-to-Case (Note 1)	$R_{\theta JC}$	75	$^\circ C/W$



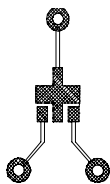
5. $T_A=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30			V
Breakdown Voltage Temp. Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$I_D=-250\mu A$ Referenced to 25°C		-22		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-24V, V_{GS}=0V$			-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ C$			-10	
Gate - Body Leakage, Forward	I_{GSSF}	$V_{GS}=20V, V_{DS}=0V$			100	nA
Gate - Body Leakage, Reverse	I_{GSSR}	$V_{GS}=-20V, V_{DS}=0V$			-100	nA
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.9	-3	V
Gate Threshold Voltage Temp. Coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	$I_D=-250\mu A$ Referenced to 25°C		4		mV/°C
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-2A$		63	80	mΩ
		$V_{GS}=-4.5V, I_D=-1.5A$		100	125	
On-State Drain Current	$I_{D(ON)}$	$V_{GS}=-10V, V_{DS}=-5V$	-10			A
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-2A$		5		S
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$		298		pF
Output Capacitance	C_{oss}			83		pF
Reverse Transfer Capacitance	C_{rss}			39		pF
SWITCHING CHARACTERISTICS (Note 2)						
Turn - On Delay Time	$t_{D(on)}$	$V_{DD}=-15V, I_D=-1A$ $V_{GS}=-10V, R_{GEN}=6\Omega$		6	12	ns
Turn - On Rise Time	t_r			13	23	ns
Turn - Off Delay Time	$t_{D(off)}$			11	20	ns
Turn - Off Fall Time	t_f			6	12	ns

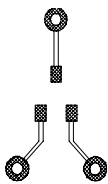


Total Gate Charge	Q _g	V _{DS} =-15V, I _D =-3.6A V _{GS} =-10V		6.2	9	nC
Gate-Source Charge	Q _{gs}			1		nC
Gate-Drain Charge	Q _{gd}			1.2		nC
Drain–Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain–Source Diode Forward Current	I _s				-0.42	A
Drain–Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _s =-0.42A (Note 2)		-0.8	-1.2	V

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.



b) 270°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%



6.1 Typical Characteristics

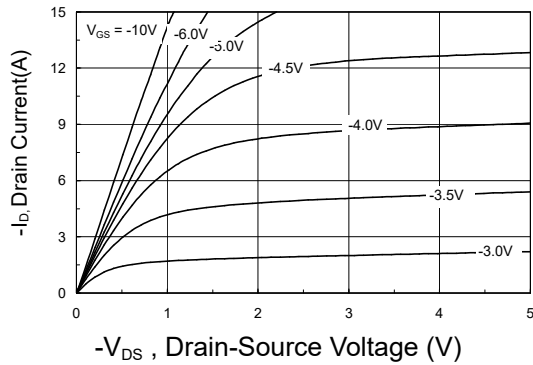


Figure 1: On-Region Characteristics.

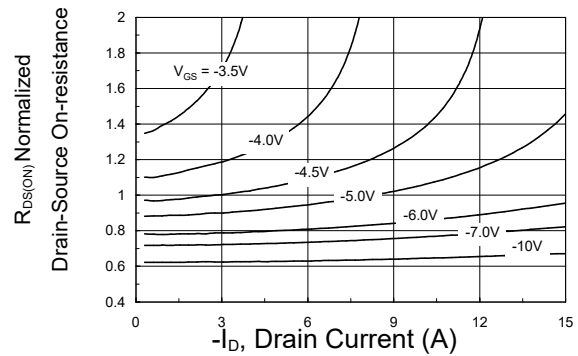


Figure 2: On-Resistance Variation with Drain Current and Gate Voltage.

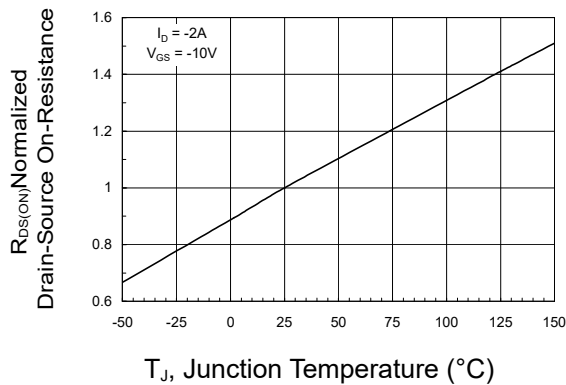


Figure 3: On-Resistance Variation with Temperature.

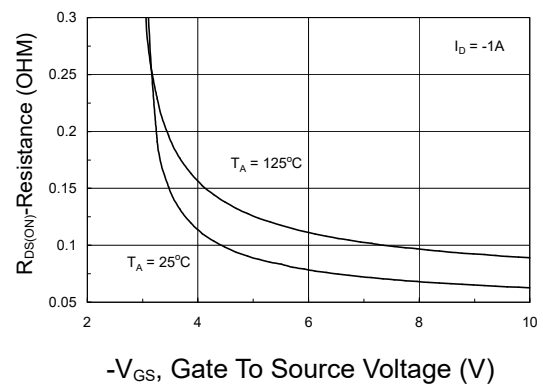


Figure 4: On-Resistance Variation with Gate-to-Source Voltage.

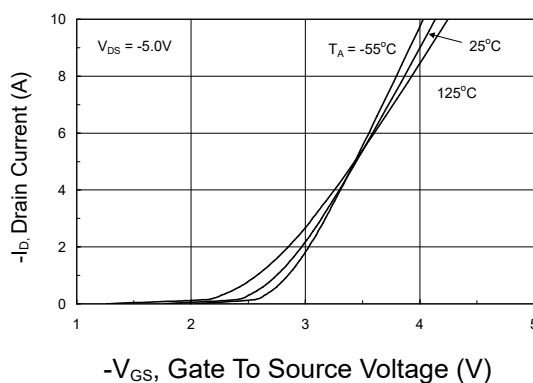


Figure 5: Transfer Characteristics.

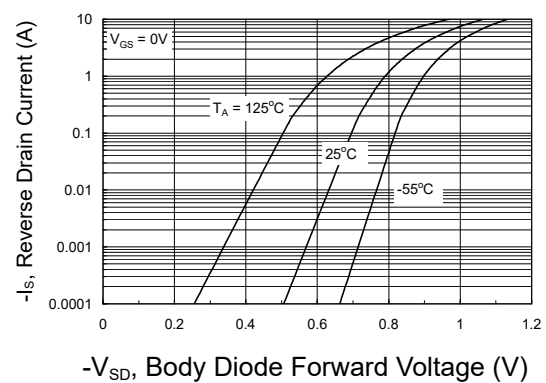


Figure 6: . Body Diode Forward Voltage Variation with Source Current and Temperature.



6.2 Typical Characteristics

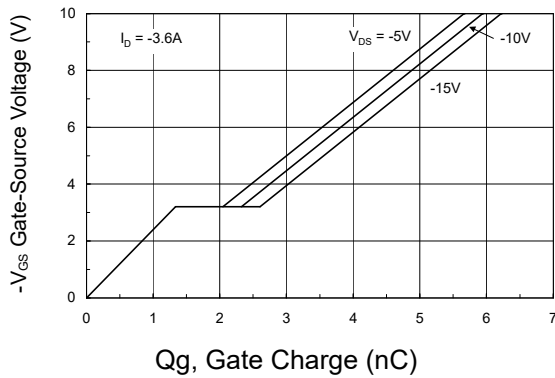


Figure 7: Gate-Charge Characteristics

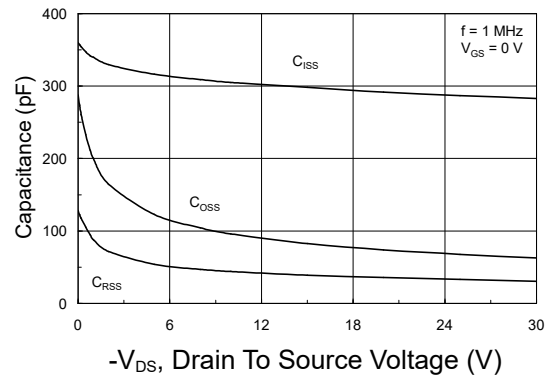


Figure 8: Capacitance Characteristics

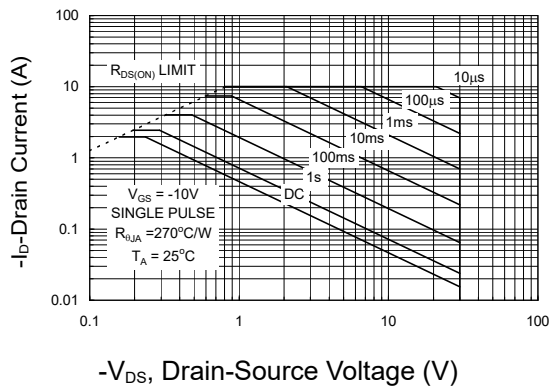


Figure 9: Maximum Safe Operating Area.

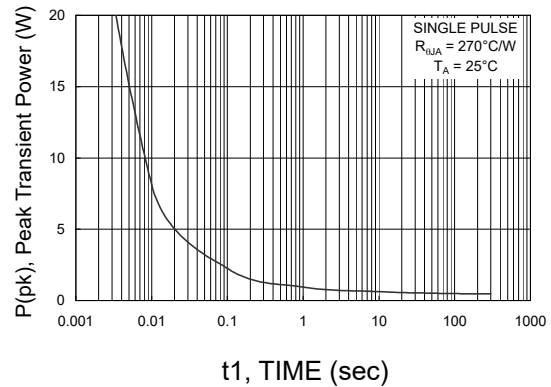


Figure 10: Single Pulse Maximum Power Dissipation.

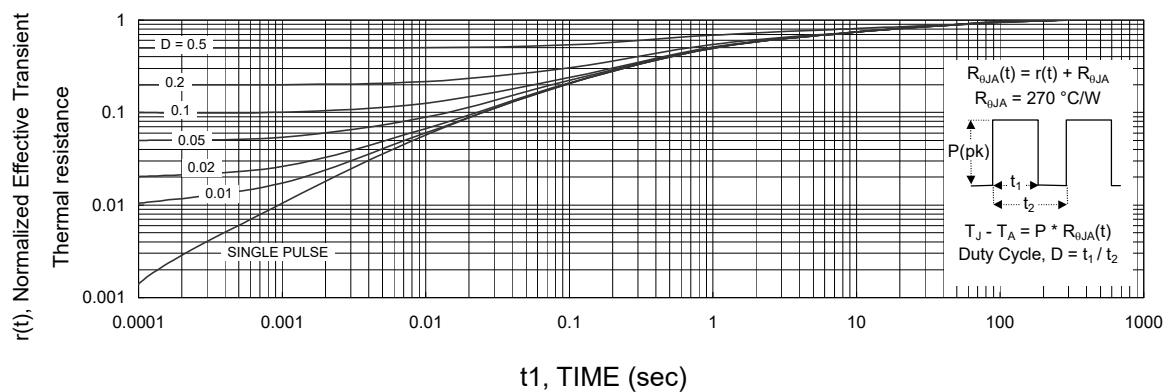
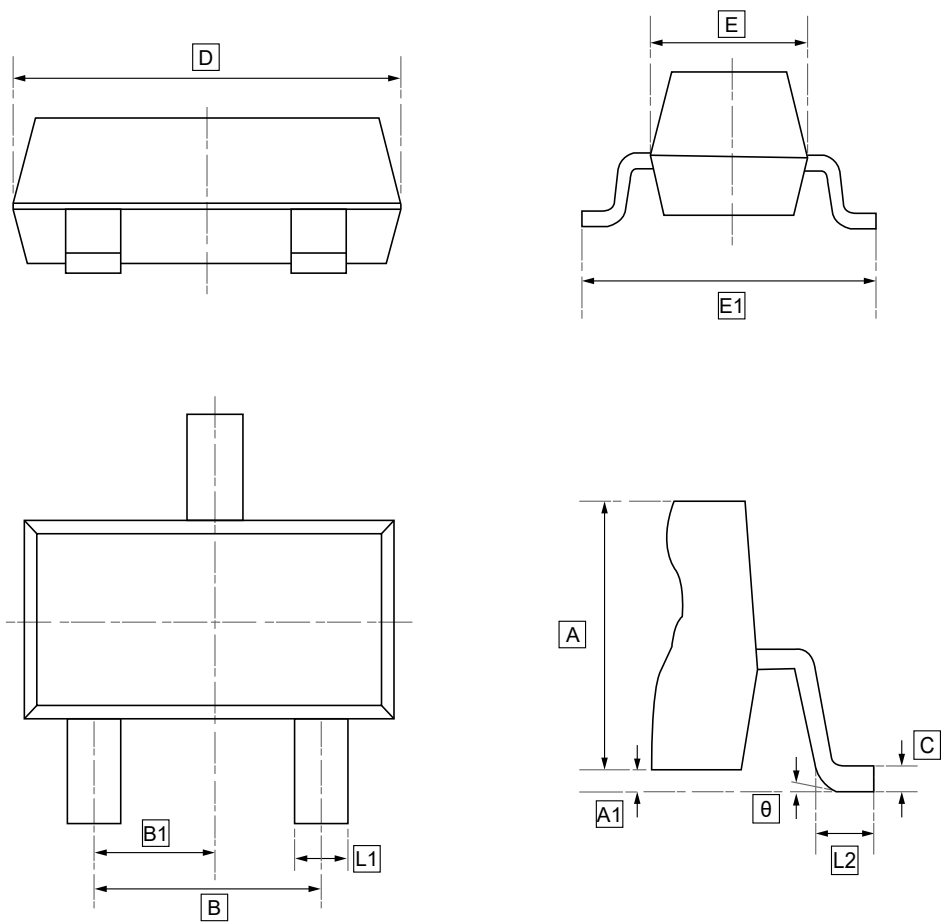


Figure 11: Transient Thermal Response Curve.



7.SOT-23 Package Outline Dimensions

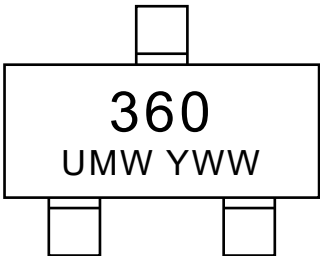


DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	L1	L2	C	D	E	E1	B	B1	θ
Min	1.050	0.000	0.300	0.350	0.100	2.820	1.500	2.700	1.800	0.950	0°
Max	1.150	0.100	0.500	0.550	0.200	3.020	1.700	2.900	2.000	TYP	8°



8.Ordering information



Order Code	Package	Base QTY	Delivery Mode
UMW FDN360P	SOT-23	3000	Tape and reel



9.Disclaimer

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

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